

**PRODUCTION DATA SHEET** 

### **DESCRIPTION**

The LX5251 is a multimode SCSI terminator that is compatible with the SCSI SPI-2 (Ultra2), SCSI SPI-3 (Ultra3 or Ultra160), and SCSI SPI-4 (Ultra320) specifications developed by the T10 standards committee for low voltage differential (LVD) termination, while providing backwards compatibility to the SCSI, SCSI-2, and SPI single-ended specifications. Multimode compatibility permits the use of legacy devices on the bus without hardware alterations. Automatic mode selection is achieved through voltage detection on the Diffsense line.

The LX5251 utilizes an industry standard LVD architecture. The individual high bandwidth drivers maximize channel separation, reduce channel-to-channel noise and cross talk to insure Ultra320 performance.

When the LX5251 is enabled, the differential sense (DIFFSENSE) pin supplies a voltage between 1.2V and 1.4V. In

application, this pin is tied to the DIFFSENSE input of the corresponding LVD transceivers. This action enables the LVD transceiver function. DIFFSENSE is capable of supplying a maximum of 15mA.

Tying the DIFFSENSE pin high places the LX5251 in a HI-Z state indicating the presence of an HVD device. Tying the pin low places the part in a single-ended mode while also signaling the multimode transceiver to operate in a single-ended mode.

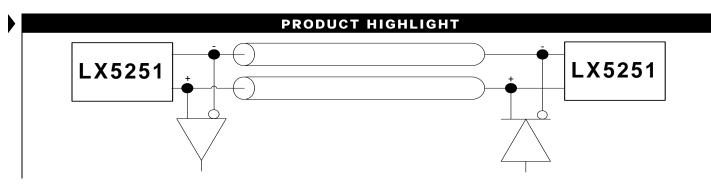
Recognizing the needs of portable and configurable peripherals, the LX5251 has a TTL compatible sleep/disable mode. During this sleep/disable mode, power dissipation is reduced to a meager 15uA while also placing all outputs in a HI-Z state. Also during sleep/disable mode, the DIFFSENSE function is disabled and is placed in a HI-Z state.

The LX5251 also provides a master / slave function. Driving this pin high or floating the pin enables the 1.3V DIFFSENSE reference. Driving the pin low disables the on board DIFFSENSE reference and enables use of an external master reference device.

## **KEY FEATURES**

- Compliant with SCSI SPI-2 (Ultra2), SPI-3 (Ultra160), and SPI-4 (Ultra320)
- Auto-Selectable LVD or Single-Ended Termination
- Fast Response, No Output Capacitors Required
- Compatible with Active Negation Drivers
- 15µA Supply Current in Disconnect Mode
- Logic Command Disconnects All Termination Lines
- Diffsense Line Driver
- Ground Driver Integrated for Single-Ended Operation
- Current Limit and Thermal Protection
- Hot-Swap Compatible (Single-Ended)
- Available in 24-pin TSSOP Package

IMPORTANT: For the most current data, consult MICROSEMI's website: http://www.microsemi.com



# PACKAGE ORDER INFO PW Plastic TSSOP 24-Pin RoHS Compliant / Pb-free Transition DC: 0442 0 to 70 LX5251CPW

Note: Available in Tape & Reel.Append the letters "TR" to the part number. (i.e. LX5251CPW-TR)



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# ABSOLUTE MAXIMUM RATINGS

Term Power (V <sub>TERM</sub> )	0.3V to 7V
Operating Junction Temperature	150°C
Storage Temperature Range	
Peak Package Solder Reflow Temperature (40 second maximum exposure)	

Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of specified terminal.

### THERMAL DATA

PW 24 Pin Plastic TSSOP

THERMAL RESISTANCE-JUNCTION TO AMBIENT,  $\theta_{JA}$ 

100°C/W

Junction Temperature Calculation:  $T_J = T_A + (P_D \times \theta_{JA})$ .

The  $\theta_{JA}$  numbers are guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.  $\theta_{JA}$  can vary significantly depending on mounting technique.

## PACKAGE PIN OUT

1+ 🖂	10	24	□□ VTERM
1- 🖂	2	23	□□ NC
2+ 🗀	3	22	<b>□</b> 9-
2- 🗀	4	21	<b>□</b> 9+
3+ 🖂	5	20	<b>□</b> 8-
3- 🗀	6	19	<b>□</b> 8+
4+ 🖂	7	18	<del></del>
4- 🗀	8	17	<b>□</b> □ 7+
5+ 🖂	9	16	<b>□</b> □ 6-
5- 🖂	10	15	<b>□</b> 6+
DISC	11	14	DIFFSENSE
GND □□	12	13	□□ M/Sb

PW PACKAGE (Top View)

N/C = Not internally connected

RoHS / Pb-free 100% Matte Tin Lead Finish

## MASTER/SLAVE FUNCTION TABLE

Master/Slave	DIFFSENSE Status		
L*	HI Z	0mA	
Н	1.3V	10mA Source	
Open (Pull-Up)	1.3V	10mA Source	

<sup>\*</sup> When in Low state, terminator will sense state of DIFFSENS line.

#### **DIFFSENSE/POWER UP/POWER DOWN FUNCTION TABLE Outputs** Quiescent DISCONNECT **DIFFSENSE** Current Status Type L < 0.5V Enable SE 55mA 0.7V - 1.9V35mA L Enable LVD > 2.4V HI-Z Disable 8mA H or Open Disable HI-Z 10μΑ



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## RECOMMENDED MAX OPERATING CONDITIONS

Parameter	Symbol	LX5251			Units
r diametei	Зупівої	Min	Тур	Max	Uillis
VTerm LVD	V	2.9		5.25	V
SE	V <sub>TERM</sub>	3.5		5.25	V
Signal Line Voltage		0		5.0	V
Disconnect Input Voltage		0		$V_{TERM}$	V
Operating Junction Temperature	TJ	0		125	°C

### **ELECTRICAL CHARACTERISTICS**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le T_{A} \le 70^{\circ}\text{C}$ , VTerm = 4.75V, and DISC = L.

	Parameter	Symbol Test Conditions		LX5251			Units	
	Parameter	Symbol	rest Conditions	Min	Тур	Max	Units	
▶ L'	VD Terminator Section							
V	Term Supply Current	LVD <sub>ICC</sub>	All term lines open DISC > 2.0V		35 15	45 35	mΑ μΑ	
С	ommon Mode Voltage	$V_{CM}$		1.125	1.25	1.375	V	
0	offset Voltage	Vos	Open circuit between (-) and (+) terminals	100	112	125	mV	
D	ifferential Terminator Impedance	Zo	V <sub>OUT</sub> Differential = -1V to +1V	100	105	110	Ω	
С	ommon Mode Impedance	Z <sub>CM</sub>	0.5V to 2V	110	150	195	Ω	
0	output Capacitance (Note 1)	Co	DISC > 2.0V			3	pF	
М	lode Change Delay	$t_{DF}$	Diffsense = 1.4V to 0V	100	115	300	ms	
D	iffsense Section			<u> </u>		•	•	
D	iffsense Output Voltage	$V_{DIFF}$		1.2	1.3	1.4	V	
D	iffsense Output Source Current	I <sub>DIFF</sub>	V <sub>DIFF</sub> = 0V	5		15	mA	
D	iffsense Sink Current	I <sub>SINK(DIFF)</sub>	V <sub>DIFF</sub> = 2.75V	20		200	μΑ	
S	ingle Ended Section			<u> </u>				
V	Term Supply Current	SE <sub>ICC</sub>	All tem lines = Open, Master/Slave = 0V All tem lines = 0.2V, Master/Slave = 0V DISC > 2.0V; T <sub>A</sub> = 25°		55 250 15	75 290 35	mA mA μA	
Te	ermination Output High Voltage	Vo		2.5	2.7	3.1	V	
0	output Current	Io	V <sub>OUT</sub> = 0.2V	18.5	22.5	24	mA	
S	ink Current	I <sub>SINK</sub>	V <sub>OUT</sub> = 4V, All lines	40	65		mA	
0	Output Capacitance (Note 1)	Co	DISC > 2.0V			3	pF	
0	Output Leakage	I <sub>DDQ</sub> I <sub>HP</sub>	DISC > 2.0V; V <sub>LINE</sub> = 0 to 4V, T <sub>A</sub> = 25° DISC > 2.0V; V <sub>TERM</sub> = Open, V <sub>LINE</sub> = 2.7V, T <sub>A</sub> = 25°		1	2	μA μA	
G	Fround Driver Impedance	Z <sub>G</sub>	I = 1mA			100	Ω	



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## **ELECTRICAL CHARACTERISTICS (CONTINUED)**

Unless otherwise specified, the following specifications apply over the operating ambient temperature  $0^{\circ}\text{C} \le T_{A} \le 125^{\circ}\text{C}$ , VTerm = 4.75V, and DISCONNECT = L.

Parameter	Symbol	Symbol Test Conditions	LX5251			Units
	Syllibol		Min	Тур	Max	UIIILS
DISCONNECT Section						
Disconnect Thresholds	$V_{TH}$		0.8		2.0	V
Input Current	I <sub>IL</sub>	DISC = 0V		100		nA
	I <sub>IH</sub>	DISC = 2.4V			10	μΑ
MASTER/SLAVE Section						
Master/Slave Thresholds	V <sub>TH(MS)</sub>		0.8		2.0	V
Input Current	I <sub>IL(MS)</sub>	Master/Slave = 0V			10	μA
Input Current	I <sub>IH(MS)</sub>	Master/Slave = 2.4V		100		nA

Note 1: Guaranteed by design.

#### **BLOCK DIAGRAM** 22.4mA 1 of 9 I-Limited Terminator 2.7V VTERM 24 Pairs Source 1.07 mA SE O LVD(-) /SF HVD O 52.5 SE -0 DISC 11 LVD LVD(+) 150 /SE (Pseudo-GND) HVD O 52.5 20 10mA 1.07 mA -Limited M/S 13 1.3V 12 GND Source ON DIFSENSE 14 MODE DISC SE LATCH HVD X LVD X

Figure 1 – LX5251 Block Diagram



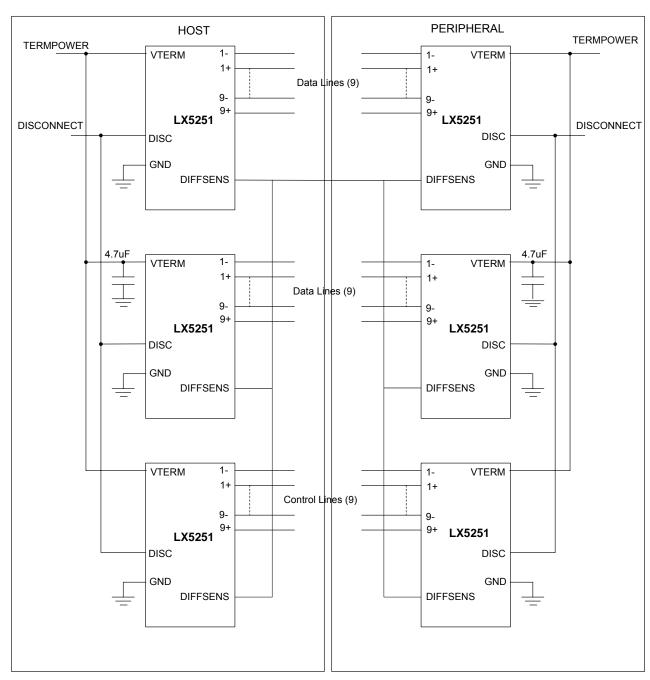
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FUNCTIONAL PIN DESCRIPTION				
PIN NAME	DESCRIPTION			
1-, 2-, 3-, 4-, 5-, 6-, 7-, 8-, 9-	Negative signal termination lines for LVD mode. Signal termination lines for SE mode.			
1+, 2+, 3+, 4+, 5+, 6+, 7+, 8+, 9+	Positive signal termination lines for LVD mode. Psuedo-ground lines for SE mode.			
$V_{TERM}$	Power supply pin for terminator. Connect to SCSI bus VTERM. Musts be decoupled by one 4.7µF low-ESR capacitor for every three terminator devices. It is absolutely necessary to connect this pin to the decoupling capacitor through a very low impedance (big traces to PCB). Keeping distances very short from the decoupling capacitors is somewhat layout dependent and some applications may benefit from high frequency decoupling with 0.1µF capacitors at V <sub>TERM</sub> pin.			
DISCONNECT	Enables/Disables terminator. See Power Down Function Table for logic levels.			
GND	Terminator ground pin. Connect to ground.			
MASTER/SLAVE	Sometimes referred to as M/S pin in this datasheet. Used to select which terminator is the controlling device. M/S pin High or Open enables the DIFFSENSE output drive. Please see MASTER/SLAVE Function Table.			
DIFFSENSE	This is a dual function pin. It drives the SCSI bus DIFFSENS line. It is also the sense pin to detect the SCSI bus mode (LVD, SE, or HVD). DIFFSENSE output drive can be disabled with low level on the M/S pin. Please see DIFFSENSE and MASTER/SLAVE Function Tables. Note: Must connect Diffsense signal to Diffsense pin of LX5251.			



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## **APPLICATION SCHEMATIC**



<sup>\*</sup> DIFFB pin not present on the LX5251CPW. Must connect Diffsense signal to Diffsens pin of each terminator.

Figure 2 – Microsemi Application Schematic

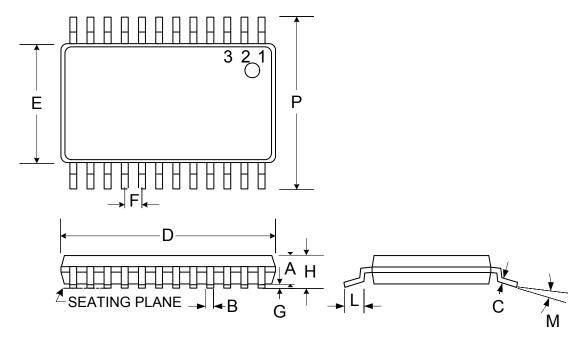


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## **MECHANICAL DRAWINGS**

 $\mathbf{PW}$ 

# 24-Pin Thin Small Shrink Outline (TSSOP)



Dim	MILLIM	ETERS	INC	HES
Dilli	MIN	MAX	MIN	MAX
Α	0.85	0.95	0.033	0.037
В	0.19	0.30	0.007	0.012
С	0.09	0.20	0.0035	0.008
D	7.70	7.90	0.303	0.311
Е	4.30	4.50	0.169	0.177
F	0.65 BSC		0.025 BSC	
G	0.05	0.15	0.002	0.005
Н	_	1.10	_	.0433
L	0.50	0.75	0.020	0.030
M	0°	8°	0°	8°
Р	6.25	6.55	0.246	0.256
*LC	_	0.10	_	0.004

## Note:

 Dimensions do not include mold flash or protrusions; these shall not exceed 0.155mm(.006") on any side. Lead dimension shall not include solder coverage.

<sup>\*</sup> Lead Coplanarity



LX5251

# 9-Line Multimode SCSI Terminator

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NOTES

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